

<p>NOMINAL FINISHED BOARD THICKNESS 0.062" +/- .005</p>	PRIMARY SILKSCREEN
	PRIMARY GOLD MASK
	PRIMARY SOLDER MASK
	PRIMARY SIDE (LAYER 1)
	GND1 PLANE (LAYER 2)
	.003"
	PWR1 PLANE (LAYER 3)
	.003"
	GND2 PLANE (LAYER 4)
	GND3 PLANE (LAYER 5)
	.003"
	PWR2 PLANE (LAYER 6)
	.003"
	GND4 PLANE (LAYER 7)
SECONDARY SIDE (LAYER 8)	
SECONDARY SOLDER MASK	
SECONDARY GOLD MASK	
SECONDARY SILKSCREEN	

NOMINAL
FINISHED
BOARD
THICKNESS
0.062"
+ / - .005

CONTROLLED IMPEDANCE ON LAYERS 1 AND 8 ONLY
CHARACTERISTIC IMPEDANCE = 50 OHMS +/- 10%
ARTWORK LINE WIDTH FOR
IMPEDANCE CONTROLLED LINES = 8.5 MILS
CHARACTERISTIC IMPEDANCE = 100 OHMS DIFF +/- 10%
ARTWORK LINE WIDTH FOR
IMPEDANCE CONTROLLED LINES = 5 MIL TRACE/5 MIL SPACE

MATERIALS; MANUFACTURING TO MEET EU ROHS DIRECTIVE, ALL MATERIALS.
INCLUDING SOLDERMASK - REFER TO EU ROHS DIRECTIVE 20002/95/ECIALS.
ISOLA 370HR OR EQUIVALENT, IN ACCORDANCE WITH IPC-L-130 (LATEST REV.).
GLASS FABRIC BASE, EPOXY RESIN, FIRE RESISTANT.

BONDING AGENT; PREIMPREGNATED B STAGE EPOXY GLASS CLOTH IN ACCORDANCE WITH
IPC-L-109 (LATEST REV.).

CLADDING; EXTERNAL LAYERS 1/2 OZ. COPPER, OVERPLATE TO 1 1/2 OZ.
INTERNAL SIGNAL LAYERS 1 OZ. COPPER.

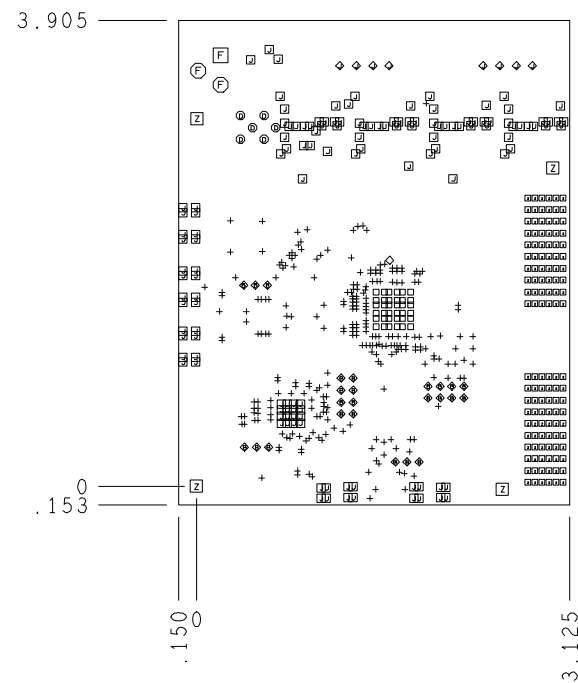
SURFACE FINISH; SILVER IMMERSION.

SOLDER MASK; SHALL BE LIQUID PHOTOIMAGABLE (LPI), COLOR BLUE, APPLIED ON BOTH SIDES OVER
BARE COPPER AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3.

SILK SCREEN; SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR WHITE.


U.L. RATING; 94VO MINIMUM.

1. REFER TO IPC-4101B/24/26/83/978/99 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
2. UNDIMENSIONED HOLES TO BE LOCATED WITHIN +/- .005 OF THEIR TRUE POSITION WITH RESPECT TO ARTWORK.
3. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
4. HOLE DIAMETERS APPLY AFTER PLATING.
5. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL, INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
6. MINIMUM DESIGN LINE WIDTH IS .005 INCH.
7. MINIMUM DESIGN SPACING IS .005 INCH.
8. BOARD/PANEL MUST MEET IPC-A-600 (LATEST REV.) CLASS 2 FOR FLATNESS.
9. MFRG. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
A. U.L. CODE D. MFRG. LOGO
B. DATE CODE (STAMP) E. SUCCESSFUL ELECTRICAL BOARD TEST.
C. FLAMMABILITY RATING
10. NON-FUNCTIONAL PADS MAY BE REMOVED FROM INNER SIGNAL LAYERS AT MFRG. DISCRETION.
11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFRG. MAY TEAR DROP PADS TO MAINTAIN ANNULAR RING AT PAD TO CIRCUIT INTERFACE ONLY AND MUST INSURE ELECTRICAL INTEGRITY.
12. REPAIRS PER IPC-R-700 ARE ALLOWED.
13. MODIFICATIONS TO THE ARTWORK, OTHER THAN THOSE DESCRIBED ON THE FABRICATION DRAWING, ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
14. CORES BETWEEN LAYERS 2 AND 4, AND LAYERS 5 AND 7 SHOULD BE NO MORE THAN 3 MILS IN THICKNESS TO HAVE OPTIMUM INNER PLANE CAPACITANCE.
15. SILKSCREEN CROSS HATCHING UNDER LFCSP PACKAGE U300 IS REQUIRED AND NOT TO BE REMOVED DURING PROCESSING.
16. ALL VIAS OF 13 MILS OR SMALLER SHOULD BE PLUGGED WITH SOLDER (PREFERRED) OR NON-CONDUCTIVE EPOXY OR SOLDERMASK.



PRIMARY SIDE

FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	10.0	PLATED	260	
□	13.0	PLATED	36	
▣	13.0	PLATED	134	
▤	28.0	PLATED	120	
◇	32.0	PLATED	1	
◆	40.0	PLATED	25	
⬢	45.0	PLATED	6	
◈	50.0	PLATED	8	
⬢	120.0	PLATED	2	
◻	140.0	PLATED	1	
◻	156.0	NON-PLATED	4	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX +- .010 +-1/32 +/- 2 .XXX +- .005			 ANALOG DEVICES		HSC DIVISION 7910 TRIAD CENTER DRIVE GREENSBORO, NC 27409	
MATERIAL			APPROVAL		DATE	
			DRAWN BY R. WILSON		04/06/10	
			DESIGNED			
			CHECKED			
FINISH			APPROVED		TITLE	
			MFG ENGINEER		FABRICATION DWG	
					AD9467 ENG. EVAL. PCB	
DO NOT SCALE DWG			SIZE	FSCM NO	DRAWING NUMBER	REV
			C		FAB_9467CE01	A
			SCALE	1/1		SHEET 1 OF 1